

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	524	chip same interposer same adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 13:55
L2	323	(chip or die) same electrode same (wire or wiring) same (mount or mounting or mounted or bond or bonding or bonded) same hole same adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 13:57
L3	48	((first or second or third or upper or lower or top or bottom) near2 (chip or die)) same electrode same (wire or wiring) same (mount or mounting or mounted or bond or bonding or bonded) same hole same adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 13:59
L4	5	((first or second or third or upper or lower or top or bottom) near2 (chip or die)) same electrode same (wire or wiring) same (mount or mounting or mounted or bond or bonding or bonded) same hole same adhesive same ((insulating or dielectric or non-conductive or nonconductive) near2 (interpose or interposing or interposer or substrate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:01
L5	22	((first or second or third or upper or lower or top or bottom) near2 (chip or die)) same electrode same (wire or wiring) same (mount or mounting or mounted or bond or bonding or bonded) same hole same adhesive same (insulating or dielectric or non-conductive or nonconductive or insulator)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:01
L6	3	((first or second or third or upper or lower or top or bottom) near2 (chip or die)) same electrode same (wire or wiring) same (mount or mounting or mounted or bond or bonding or bonded) same hole same adhesive same (insulating or dielectric or non-conductive or nonconductive or insulator)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:01

L7	149520	(first or second or third or upper or lower or top or bottom) near3 (chip or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:02
L8	7	(first or second or third or upper or lower or top or bottom) near3 (chip or die) with interposer with adhesive with hole	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:02
L9	6	(first or second or third or upper or lower or top or bottom) near3 (chip or die) with interposer with adhesive with hole with (mount or mounting or mounted or bond or bonded or bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:03
L10	107	(first or second or third or upper or lower or top or bottom) near3 (chip or die) with adhesive with hole with (mount or mounting or mounted or bond or bonded or bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:07
L11	27	(first or second or third or upper or lower or top or bottom) near3 (chip or die) with adhesive with hole with (mount or mounting or mounted or bond or bonded or bonding) and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:09
L12	18	(first or second or third or upper or lower or top or bottom) near3 (chip or die) with adhesive with hole with (mount or mounting or mounted or bond or bonded or bonding) and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685) and ((substrate or interpose or interposing or nonconductive or non-conductive or insulating or insulator or dielectric) near5 hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:10

L13	18	(first or second or third or upper or lower or top or bottom) near3 (chip or die) with adhesive with hole with (mount or mounting or mounted or bond or bonded or bonding) and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685) and ((substrate or interpose or interposing or nonconductive or non-conductive or insulating or insulator or dielectric) near5 hole) and (wire or wiring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:10
L14	14	(first or second or third or upper or lower or top or bottom) near3 (chip or die) with adhesive with hole with (mount or mounting or mounted or bond or bonded or bonding) and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685) and ((substrate or interpose or interposing or nonconductive or non-conductive or insulating or insulator or dielectric) near5 hole) and (wire or wiring).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:11
L15	9	(first or second or third or upper or lower or top or bottom) near3 (chip or die) with adhesive with hole with (mount or mounting or mounted or bond or bonded or bonding) and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685) and ((substrate or interpose or interposing or nonconductive or non-conductive or insulating or insulator or dielectric) near5 hole).clm. and (wire or wiring).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:11

L16	3	(first or second or third or upper or lower or top or bottom) near3 (chip or die) with adhesive with hole with (mount or mounting or mounted or bond or bonded or bonding).clm. and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685) and ((substrate or interpose or interposing or nonconductive or non-conductive or insulating or insulator or dielectric) near5 hole). clm. and (wire or wiring).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:11
L17	4	(first or second or third or upper or lower or top or bottom) near3 (chip or die) with adhesive with hole with (mount or mounting or mounted or bond or bonded or bonding).clm. and ((substrate or interpose or interposing or nonconductive or non-conductive or insulating or insulator or dielectric) near5 hole).clm. and (wire or wiring).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:12
L18	32010	((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:13
L19	32734	((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die)) with (mount or mounted or mounting or bond or bonded or bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:13
L20	32734	((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) with (mount or mounted or mounting or bond or bonded or bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:14
L21	2707	((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) with (mount or mounted or mounting or bond or bonded or bonding) with adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:14

L22	105	(((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) with (mount or mounted or mounting or bond or bonded or bonding) with adhesive with (interposer or interposing or ((insulating or dielectric or nonconductive or non-conductive) near3 substrate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:15
L23	24	(((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) with (mount or mounted or mounting or bond or bonded or bonding) with adhesive with (interposer or interposing or ((insulating or dielectric or nonconductive or non-conductive) near3 substrate)) with electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:15
L24	16	(((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) with (mount or mounted or mounting or bond or bonded or bonding) with adhesive with (interposer or interposing or ((insulating or dielectric or nonconductive or non-conductive) near3 substrate)) with electrode with (wire or wiring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:15
L25	11	(((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) with (mount or mounted or mounting or bond or bonded or bonding) with adhesive with ((interposer or interposing or ((insulating or dielectric or nonconductive or non-conductive) near3 substrate)) with hole) same electrode same (wire or wiring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:16
L26	11	(((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) same (mount or mounted or mounting or bond or bonded or bonding) with adhesive with ((interposer or interposing or ((insulating or dielectric or nonconductive or non-conductive) near3 substrate)) with hole) same electrode same (wire or wiring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:16

L27	12	(((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) same (mount or mounted or mounting or bond or bonded or bonding) same adhesive same ((interposer or interposing or ((insulating or dielectric or nonconductive or non-conductive) near3 substrate)) with hole) same electrode same (wire or wiring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:20
L28	12	(((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) same (stack or stacking or stacked or mount or mounted or mounting or bond or bonded or bonding) same adhesive same ((interposer or interposing or ((insulating or dielectric or nonconductive or non-conductive) near3 substrate)) with hole) same electrode same (wire or wiring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:20
L29	51	(((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) same (stack or stacking or stacked or mount or mounted or mounting or bond or bonded or bonding) same adhesive same ((interposer or interposing or ((insulating or dielectric or nonconductive or non-conductive) near3 substrate))) same electrode same (wire or wiring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:22
L30	31	(((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) same (stack or stacking or stacked or mount or mounted or mounting or bond or bonded or bonding) same adhesive same ((interposer or interposing or ((insulating or dielectric or nonconductive or non-conductive) near3 substrate))) same electrode same (wire or wiring) and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:24

L31	16	(((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) same (stack or stacking or stacked or mount or mounted or mounting or bond or bonded or bonding) same adhesive same ((interposer or interposing or ((insulating or dielectric or nonconductive or non-conductive) near3 substrate))) same electrode same (wire or wiring) and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685) and (interposer or interposing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:24
L32	1	(((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) same (stack or stacking or stacked or mount or mounted or mounting or bond or bonded or bonding) same adhesive same ((interposer or interposing or ((insulating or dielectric or nonconductive or non-conductive) near3 substrate))) same electrode same (wire or wiring)).clm. and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685) and (interposer or interposing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:25
L33	1	(((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) same (stack or stacking or stacked or mount or mounted or mounting or bond or bonded or bonding) same adhesive same ((interposer or interposing or ((insulating or dielectric or nonconductive or non-conductive) near3 substrate))) same electrode same (wire or wiring)).ti,ab,clm. and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685) and (interposer or interposing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:25

L34	3	(((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) same (stack or stacking or stacked or mount or mounted or mounting or bond or bonded or bonding) same adhesive same ((interposer or interposing or ((insulating or dielectric or nonconductive or non-conductive) near3 substrate))) same electrode same (wire or wiring)).ti,ab,clm. and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:26
L35	13	(((first or second or upper or lower or top or bottom or upper or lower) near3 (chip or die))) same (stack or stacking or stacked or mount or mounted or mounting or bond or bonded or bonding) same adhesive same ((interposer or interposing or ((insulating or dielectric or nonconductive or non-conductive) near3 substrate))) same electrode same (wire or wiring)).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:26

L47	146	146 and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:28
L48	132	146 and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685) and (mount or mounting or mounted or bond or bonding or bonded or stack or stacking or stacked).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:28
L49	40	146 and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685) and (mount or mounting or mounted or bond or bonding or bonded or stack or stacking or stacked).clm. and electrode.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:28
L50	35	146 and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685) and (mount or mounting or mounted or bond or bonding or bonded or stack or stacking or stacked).clm. and electrode.clm. and (wire or wiring).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:29
L51	6	146 and (257/686 or 257/687 or 257/678 or 257/777 or 257/778 or 257/776 or 257/679 or 257/677 or 257/685) and (mount or mounting or mounted or bond or bonding or bonded or stack or stacking or stacked).clm. and electrode.clm. and (wire or wiring).clm. and interposer.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 14:29